

3 Component Replacement

3.1 Leaded Components

Whenever components are removed from or fitted to the PCB, care must be taken to avoid damage to the track. The two satisfactory methods of removing components from PTH PCBs are detailed below.

Note: The first method requires the use of a desoldering station, e.g. Philips SBC 314 or Pace MBT-100E.

3.1.1 Desoldering Iron Method

Place the tip over the lead and, as the solder starts to melt, move the tip in a circular motion.

Start the suction and continue the movement until 3 or 4 circles have been completed.

Remove the tip while continuing suction to ensure that all solder is removed from the joint, then stop the suction.

Before pulling the lead out, ensure it is not stuck to the plating.

If the lead is still not free, resolder the joint and try again.

Note: The desoldering iron does not usually have enough heat to desolder leads from the ground plane. Additional heat may be applied by holding a soldering iron on the tip of the desoldering iron (this may require some additional help).

3.1.2 Component Cutting Method

Cut the leads on the component side of the PCB.

Heat the solder joint **sufficiently** to allow **easy** removal of the lead by drawing it out from the component side: do **not** use undue force.

Fill the hole with solder and then clear with solderwick.

3.2 Surface Mount Devices

**Caution:**

Surface mount devices (SMD's) require special storage, handling, removal and replacement techniques. This equipment should be serviced only by an approved Tait Dealer or Service Centre equipped with the necessary facilities. Repairs attempted with incorrect equipment or by untrained personnel may result in permanent damage. If in doubt, contact Tait Electronics Ltd or your nearest Tait Branch or Subsidiary.